



Version: 1 Issued Date: 2022/5/5

Datasheet

产品名称 (Product): <u>BT 5.0 module</u>

产品型号 (Model No.): <u>HOLYIOT-21014 -nRF52810</u>

1. Description	 3
1. Description Hardware :	 3
Features :	 3
2. Introduction	
2.1 Programmer	 5
2.2 Software development Tool	 5
2.3 Protocols	 5
2.4 SoftDevices	 5
3. Product Descriptions	 6
3.1 Real drawings	6
3.2 Mechanical drawings	7
4. Miscellaneous	
5. Absolute maximum ratings	8

1. Description

HOLYIOT-21014 BLE module is based on Nordic nRF52810 SoC, the nRF52810 SoC is a powerful, highly flexible ultra-low power multi-protocol SoC ideally suited for Bluetooth® low energy (previously called Bluetooth Smart), ANT and 2.4GHz ultra low-power wireless applications. The nRF52810 SoC is built around a 32-bit ARM® Cortex™-M4F CPU with 192kB + 24kB RAM. The embedded 2.4GHz transceiver supports Bluetooth low energy, ANT and proprietary 2.4 GHz protocol stack. It is on air compatible with the nRF51 Series, nRF24L and nRF24AP Series products from Nordic Semiconductor.

Processing power

Multiprotocol radio (bluetooth low energy, ANT, 2.4G proprietary)

Power efficiency

Hardware:

SWD programmer (SWDIO,SWCLK,VDD,GND) nRF52810-QFAA-QFN48 LIS2DH12

Size : 25mm*25mm BLE stack & RF 2.4Ghz

Features:

Single chip, highly flexible, 2.4 GHz multi-protocol SoC 32-bit ARM Cortex-M4F Processor 1.7v to 3.6v operation 192kB flash + 24kB RAM Supports concurrent Bluetooth low energy/ANT protocol operation Up to +4dBm output power -96dBm sensitivity, Bluetooth low energy Thread safe and run-time protected Event driven API On air compatible with nRF24L and nRF24AP series 2 data rates (2Mbps/1Mbps)

PPI - maximum flexibility for power-efficient applications and code simplification

Automated power management system with automatic power management of each peripheral

Configurable I/O mapping for analog and digital I/O

3 x Master/Slave SPI

2 x Two-wire interface (I²C)

UART (RTS/CTS)

3 x PWM

AES HW encryption

Real Time Counter (RTC)

Digital microphone interface (PDM)

On-chip balun

Application:

- ·Internet of Things (IoT)
- ·SmartHome sensors
- ·Computer peripherals
- ·A4WP 'Rezence' wireless charging
- ·Sports and fitness sensors and hubs
- ·Smart watches
- ·Interactive games
- ·Wearables
- ·Connected white goods
- ·Voice-command smart remotes
- ·Beacons
- ·Connected health products
- ·RC Toys
- ·Building automation and sensor networks

2. Introduction

2.1 Programmer

HOLYIOT-21014 module use the Serial Wire Debug(SWD port), the module which layout the SWDIO, SWCLK, VDD, GND for debug and flash your own firmware, more info about the SWD, please visit https://www.silabs.com/community/mcu/32-bit/knowledge-base.entry.html/2014/10/21/serial wire debugs-qKCT

You can using the Jlink or Jtag for programmer.

2.2 Software development Tool

It supports the standard Nordic Software Development Tool-chain using Segger Embedded Studio, Keil, IAR and GCC. More info please visit https://www.nordicsemi.com/Software-and-Tools/Development-Tools

2.3 Protocols

This module support Bluetooth 5, Bluetooth Low Energy, Bluetooth mesh, Thread, 802.15.4, ANT, 2.4GHz proprietary. So we can use different protocols for different situations.

Software Development Kit

Nordic Semiconductor's Software Development Kits (SDK) are your starting point for software development on the nRF51 and nRF52 Series. It contains source code libraries and example applications covering wireless functions, libraries for all peripherals, bootloaders, wired and OTA FW upgrades, RTOS examples, serialization libraries.

More info please visit https://www.nordicsemi.com/Software-and-Tools/Software/nRF5-SDK
You can also download the SDK for coding development .

2.4 SoftDevices

Nordic Semiconductor protocol stacks are known as SoftDevices. SoftDevices are precompiled, pre-linked binary files. SoftDevices can be programmed in nRF5 series devices, and are freely downloadable from the Nordic website. Please download that here:

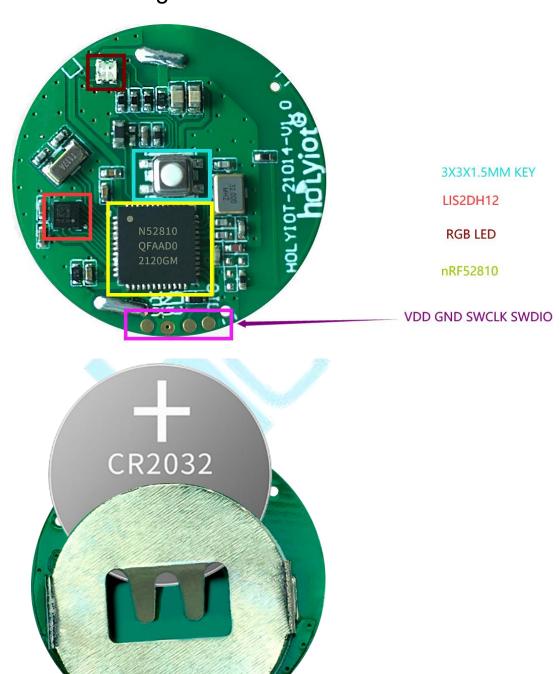
https://www.nordicsemi.com/Software-and-Tools/Software/S132

Over-The-Air DFU

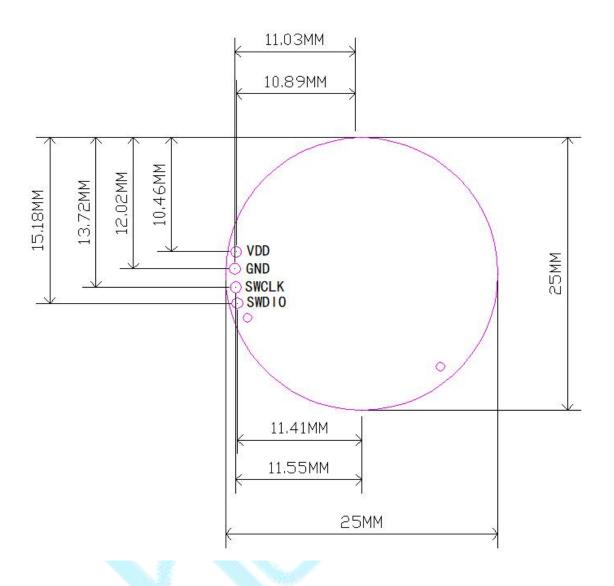
The SoC is supported by an Over-The-Air Device Firmware Upgrade (OTA DFU) feature. This allows for in the field updates of application software and SoftDevice.

3. Product Descriptions

3.1 Real drawings



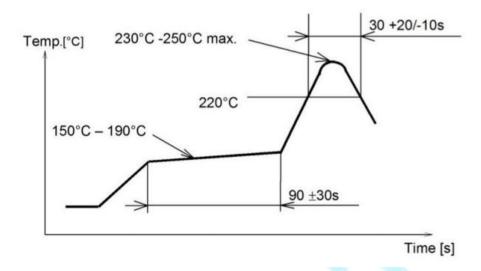
3.2 Mechanical drawings



PIN No.	PIN define	Functions	
1	VDD	power	
2	GND	Ground	
3	SWCLK	Digital I/O²(serial wire debug)	
4	SWDIO	Digital input(serial wire debug)	

4. Miscellaneous

Soldering Temperature-Time Profile for Re-Flow Soldering. Maximum number of cycles for reflow is 2. No opposite side re-flow is allowed due to module weight.



5. Absolute maximum ratings

Maximum ratings are the extreme limits to which the chip can be exposed for a limited amount of time without permanently damaging it. Exposure to absolute maximum ratings for prolonged periods of time may affect the reliability of the device.

Absolute maximum ratings:

	Min.	Max.	Unit
Supply voltages	III AAAA I		
VDD	-0.3	+3.9	٧
VSS		0	v
I/O pin voltage			
V _{VO} , VDD ≤3.6 V	-0.3	VDD + 0.3 V	V
V _{VO} , VDD >3.6 V	-0.3	3.9 V	V
NFC antenna pin current			
I _{NFC1/2}		80	mA
Radio			
RF input level		10	dBm
Environmental QFN48, 6×6 mm package			
Storage temperature	-40	+125	*C
MSL (moisture sensitivity level)		2	
ESD HBM (human body model)		4	kV
ESD CDM (charged device model)		1000	V
Environmental WLCSP, 3.0×3.2 mm package			
Storage temperature	-40	+125	*c
MSL		1	
ESD HBM		2	kV
ESD CDM		500	V
Flash memory			
Endurance	10 000		Write/erase cycles
Retention	10 years at 40°C		



